



Material Content Data Sheet



Sales Product Name		TLD1124EL		Issued		25. September 2017		
MA#		MA001137054						
Package		PG-SSOP-14-5		Weight*		82.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.376	1.66	1.66	16632	16632
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8326	
wire	non noble metal	copper	7440-50-8	27.978	33.81	34.69	338076	346922
	non noble metal	copper	7440-50-8	0.069	0.08	0.08	831	831
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1217
encapsulation	plastics	epoxy resin	-	4.634	5.60		56000	
	inorganic material	silicondioxide	60676-86-0	45.638	55.15	60.87	551483	608700
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11795	11795
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9276	9276
glue	plastics	epoxy resin	-	0.121	0.15		1461	
	noble metal	silver	7440-22-4	0.363	0.44	0.59	4383	5844
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com